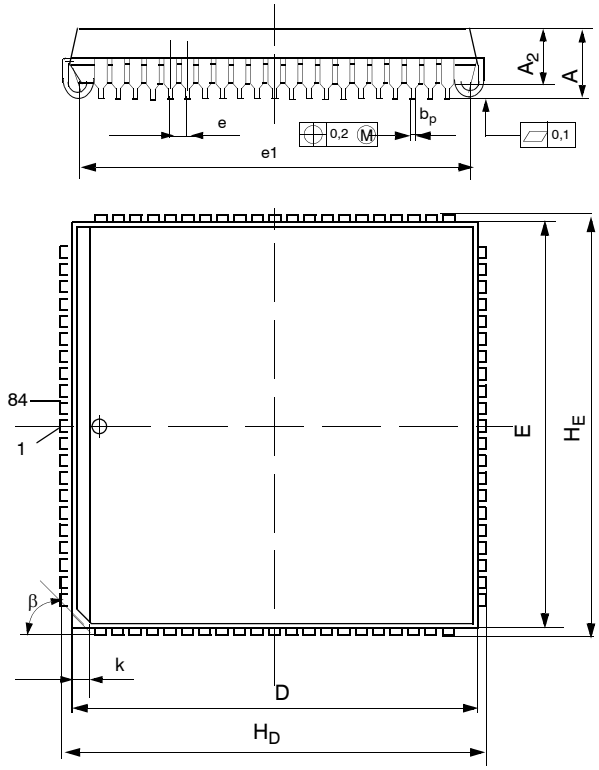
ZMD	**Package PLCC84**	**MDS 724**

Supersedes
Edition 03.92
1. Amendment 02.93

Dimensions in millimetres

Based on IEC 191-2Q: Type 112E13

1 Dimensions



Dimensions of Sub-Group B1	
A_{max}	5,10
b_{Pmin}	0,33
b_{Pmax}	0,53
e_{nom}	1,27
H_{Dmin}	30,10
H_{Dmax}	30,40
H_{Emin}	30,10
H_{Emax}	30,40

Dimensions of Sub-Group C1	
A_{min}	4,19
A_{2min}	3,10
A_{2max}	3,91
D_{min}	29,13
D_{max}	29,41
E_{min}	29,13
E_{max}	29,41
k_{min}	1,00
β	45°
e_{1min}	27,68
e_{1max}	28,70

2 Weight ≤ 6,9 g

3 Package Body Material Low Stress Epoxy

4 Lead Material FeNi-Alloy or Cu-Alloy

5 Lead Finish solder plating

6 Lead Form J-bends

Zentrum Mikroelektronik Dresden AG		
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